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TITLE: Semiconductor package using heat-radiating plate

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PATENT-FAMILY:

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ABSTRACTED-PUB-NO: KR2001008825A

BASIC-ABSTRACT:

NOVELTY - A semiconductor package using a heat-radiating plate is provided to effectively radiate heat generated from a semiconductor chip through a groove part and a protrusion part formed on upper and lower surfaces of the heat-radiating plate.

DETAILED DESCRIPTION - A semiconductor package using a heat-radiating plate comprises a semiconductor chip(15), a lead frame(11), a heat-radiating plate(13) and a molding resin(17). The semiconductor chip includes a plurality of bonding pads electrically connected to the exterior, in which electrical

• devices are integrated. The lead frame is established near the semiconductor chip and includes a lead having a plurality of electrical connection terminals whose one end is connected to the bonding pad by a wire bonding and the other end is protruded to the exterior. The heat-radiating plate includes a plurality of protrusions(13b) on at least one surface so that the heat-radiating plate supports the semiconductor chip and radiates heat. The molding resin encapsulates the semiconductor chip, the heat-radiating plate and the lead frame.

CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS: SEMICONDUCTOR PACKAGE HEAT RADIATE PLATE

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